

**Features:**

- Isolated mounting base 2500V~
- Simple design, Module and SCR rectifier bridge, Small volume, light weight

Typical Applications:

- Supplies for DC power equipment
- Field supply for DC motors
- Inverter welder

V _{DRM} /V _{RRM}	Type & Outline
600V	MDST75-06-225H6
800V	MDST75-08-225H6
1000V	MDST75-10-225H6
1200V	MDST75-12-225H6
1400V	MDST75-14-225H6
1600V	MDST75-16-225H6
1800V	MDST75-18-225H6

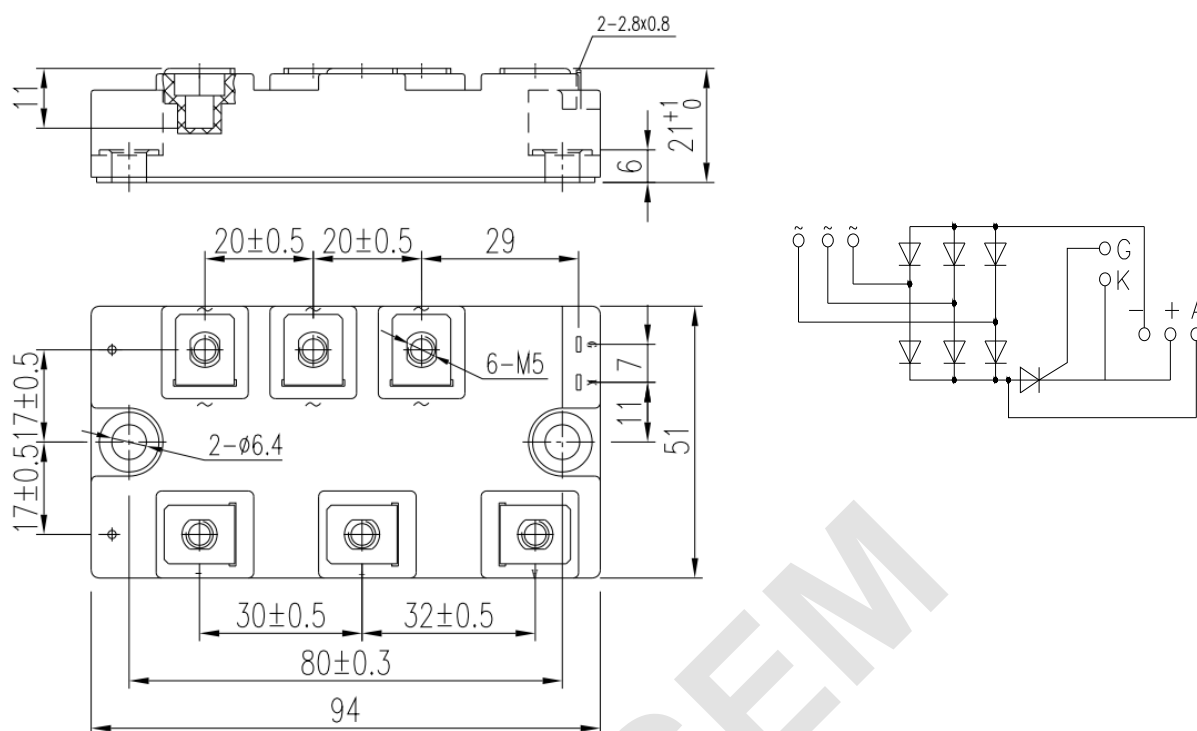
Diode

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _D	DC output current	Three-phase full wave rectifying circuit, T _C =100°C	125			75	A
V _{RRM}	Repetitive peak reverse voltage	tp=10ms	125	600		1600	V
I _{RRM}	Repetitive peak current	at V _{RRM}	125			8	mA
I _{FSM}	Surge forward current	10ms half sine wave	125			0.5	kA
I ² t	I ² t for fusing coordination	V _R =0				1.25	A ² s*10 ³
V _{FO}	Threshold voltage		125			0.85	V
r _F	Forward slope resistance					3.10	m
V _{FM}	Peak forward voltage	I _{FM} =75A	25			1.25	V
R _{th(j-c)}	Thermal resistance Junction to case	Single side cooled, per chip				0.25	°C /W
R _{th(c-h)}	Thermal resistance case to heatsink	Single side cooled, per chip				0.08	°C /W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} :1mA(max)		3000			V
F _m	Terminal connection torque(M5)			2.5		4.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T _{vj}	Junction temperature			-40		125	°C
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight					220	g
Outline	225H6						

Thyristor

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{T(AV)}	Mean on-state current	180° half sine wave 50Hz Single side cooled, T _c =100°C	125			75	A
V _{DRM} V _{R_{RRM}}	Repetitive peak off-state voltage Repetitive peak reverse voltage	tp=10ms	125	600		1600	V
I _{DRM} I _{R_{RRM}}	Repetitive peak current	at V _{DRM} at V _{R_{RRM}}	125			15	mA
I _{TSM}	Surge on-state current	10ms half sine wave	125			0.5	kA
I ² t	I ² t for fusing coordination	V _R =60%V _{R_{RRM}}					1.25
V _{TO}	Threshold voltage		125			0.85	V
r _T	On-state slope resistance						3.10
I _{GT}	Gate trigger current	V _A =12V, I _A =1A	25	30		200	mA
V _{GT}	Gate trigger voltage			0.6		2.5	V
I _H	Holding current			10		250	mA
I _L	Latching current					1000	mA
V _{GD}	Non-trigger gate voltage	V _{DM} =67%V _{DRM}	125			0.30	V
V _{TM}	Peak on-state voltage	I _{TM} =230A				1.60	V
dv/dt	Critical rate of rise of off-state voltage	V _{DM} =67%V _{DRM}	125			500	V/μs
R _{th(j-c)}	Thermal resistance Junction to case	Single side cooled, per chip				0.40	°C/W
R _{th(c-h)}	Thermal resistance case to heatsink	Single side cooled, per chip				0.13	°C/W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} : 1mA(MAX)		3000			V
F _m	Terminal connection torque(M5)			2.5		4.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				220		g
Outline	225H6						

Outline :



Unmarked dimensional tolerance: $\pm 0.5\text{mm}$